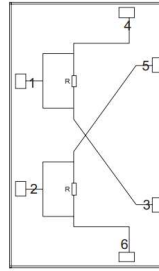


### Performance

- Frequency: 6~18GHz
- Insertion loss: 1.1dB
- Chip size: 1.60\*2.70\*0.1mm

### Function Diagram

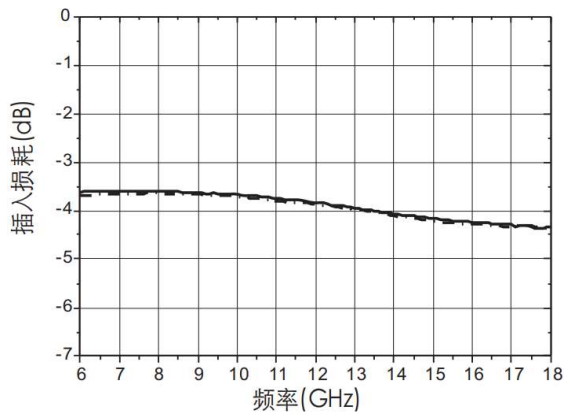


### Electrical Specifications (Ta=+25°C, 50Ω system)

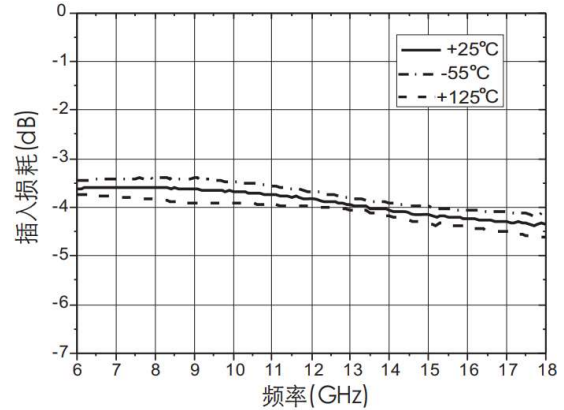
Parameter	Min	Typical	Max	Unit
Frequency Range	6~18			GHz
Insertion Loss	-	1.1	1.5	dB
Insertion Loss Ripple	-	±0.4	-	dB
Isolation	17	22	-	dB
Input Return Loss	15	20	-	dB
Output Return Loss	17	25	-	dB
Phase Balance	-	2	3	°

### Test Curves

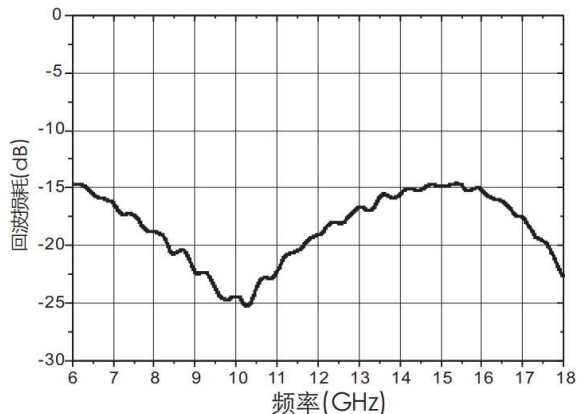
Insertion loss vs. Freq



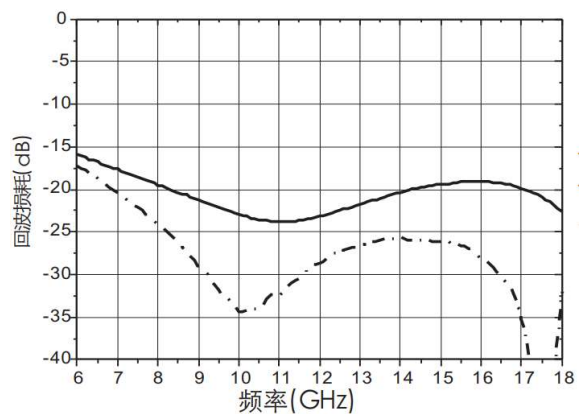
Insertion loss vs. Freq

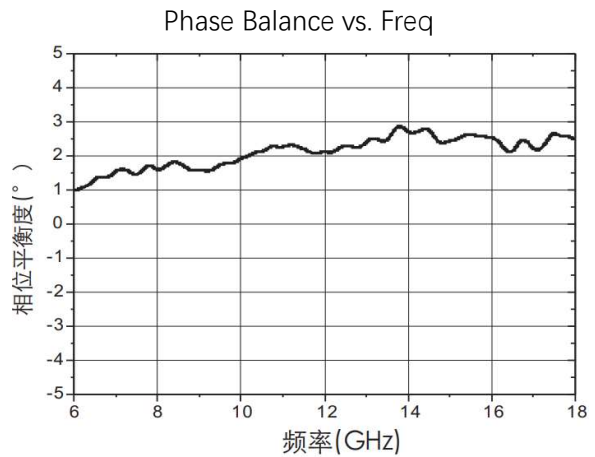
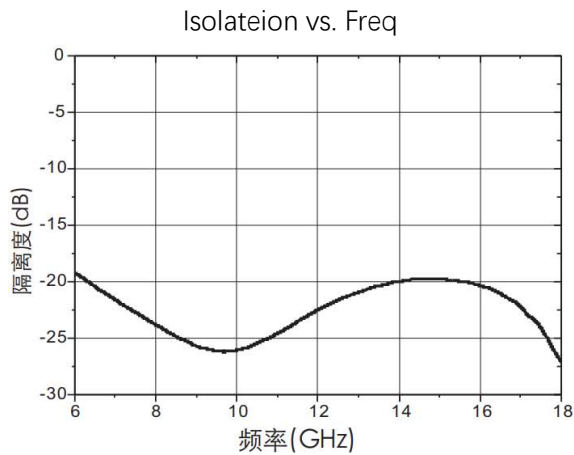


Input Return Loss vs. Freq



Output Return Loss vs. Freq

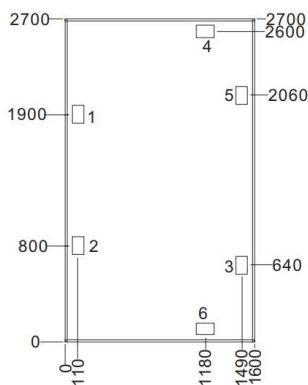




### Absolute Max Ratings

Parameter	Value
Input Signal Power	+30dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Junction Temperature	175°C
Static protection Grade (HBM)	Class 1B

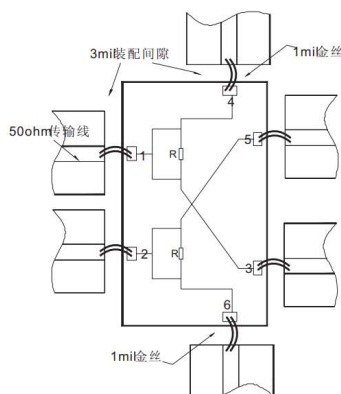
### Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated  
Pads size: 120\*100 um
5. Don't bonding on thru holds
6. Tolerance: ±50um

### Assembly Diagram



### Bonding Definition

No.	Symbol	Description
1	IN	RF input, 50ohm
2,3,4	Out1,Out2,Out3	RF Output,50ohm
-	GND	Bottom must be grounded